

# Optical multiplexers gain wider packaging & assembly options

New versions of the popular multiplexer product have been released including a new Tap Case package and additional fibre assembly options, extending the mounting options for CWDM (coarse wave division multiplexing) multiplexers in fibre-to-the-node and fibre-to-the-home applications.

Tap Case miniature packaging alternatives are available off the shelf and at no extra cost. Overall dimensions of the package (15.1 x 8.8 x 4.7mm L x H x W) are almost the same as existing ultra small multiplexers, but the new option features two integrally moulded webs with 2.7mm diameter holes for fixing to panels, trays and other frameworks. It is an ideal mounting solution in roadside cabinets where space is limited and where continuously higher levels of shock and vibration are encountered. In addition, both the standard and Tap Case

packages are available with new 'Y' and 'V' type fibre assembly variants, as well the standard fibre ribbon. The Y type provides a neat fibre exit where space is limited and high mechanical resistance is not required, whilst V type assembly is suited to simple customer side panel and rack mounting. Here, higher mechanical resistance is mandatory for handling and other environmental reasons.

These new mounting and assembly variants are available with six models in Omron's single mode mux product line – the industry's smallest

mass-produced devices compliant with Telcordia GR1221. Omron P1X4A (4 channel) and P1X8A (8 channel) multiplexers use a simplified architecture to achieve the world's smallest size. This, along with a miniature multi-layer thin film filter combined in a proprietary structure, ensure cost-competitive performance in a miniature form factor. Both are available with optional connectors to fit a wide range of network requirements, and are currently available to order.

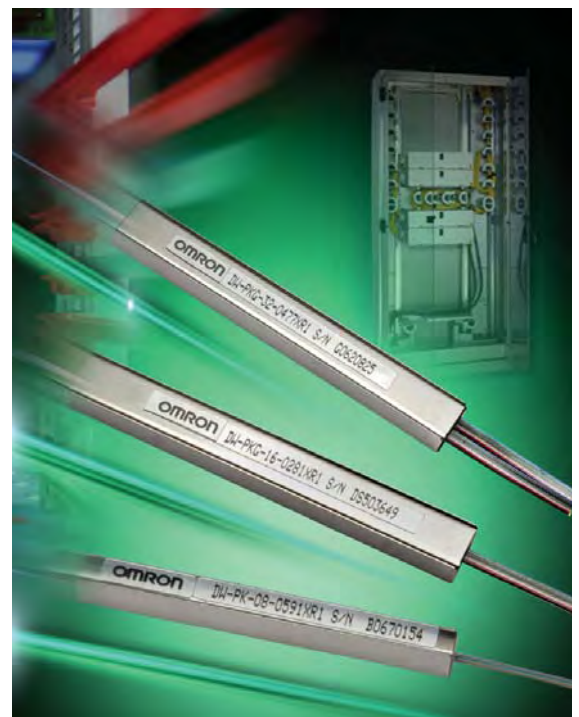


# PLC Splitter Modules improve PON reliability

Omron's new bi-directional PLC splitter modules can improve the reliability of FTTx Passive Optical Networks, DWDM and CWDM systems, optical cable TV and other outside equipment connections.

The introduction of the new Omron P1C silica on silica planar waveguide device (PLC) splitters follows the recent acquisition of NHK Spring Optical Communications Components Business. Each device is a packaged optical waveguide chip based on patented plasma chemical vapour deposition (P-CVD) technology. The combination of PLC structure and P-CVD process technology provide exceptional stable optical characteristics and superior reliability compared with fibre biconical taper (FBT) technology. In addition the splitter modules exhibit low insertion loss, low polarisation dependent loss and high port uniformity. The splitters are tested to Telcordia GR1209 and GR1221.

Modules available include 1x4, 1x8 and 1x16, 1x32, with a 1x64 planned for mid 2007. Optional custom packaging, metal fittings and connectorised cassette modules also available. All products immediately available to order



# Mark Jones, our new COO, embraces changes that are taking place in the industry

“ The past six months have been a real learning experience and I feel as though I have jumped aboard a fast moving train. I have travelled right across Europe and have met with many customers, distributors and Omron employees whose feedback has been invaluable. The achievements of OCB-EU under Nigel Blakeway’s leadership are quite apparent and commendable, and have provided me with a platform to take the company to the next phase of development. ”



**Mark Jones**  
OCB-EU Chief Operating Officer (COO)

My role is to establish a future direction for OCB-EU and the best way to do this is by listening to what is actually happening within the business and the industry as a whole. The electronics industry is seeing a massive change but it is not as visible as people think. If you have read or listened to media

commentators recently there is a picture of doom and gloom surrounding the electronics industry in Europe, but I see a rather different scene. There is an obvious production transfer of high volume repetitive applications through CEMs and subcontractors in low labour cost countries, such as China and Vietnam, but the reference technology remains very much in Europe and Omron has an important role to play in this field.

Many of our customers today are what we term ‘multi-site customers’, where design engineering, manufacturing, value added services, subcontracting and contract negotiation are all conducted in different locations. Addressing their individual requirements in different locations demands high levels of flexibility on our part, with the ability to move quickly and follow the customer all the way through the chain to the local sales level.

The implementation of a new Global Management Team for Electronic Components

Business (ECB) demonstrates that we are very much a global ‘borderless’ organisation with the infrastructure in place to manage quantum change in the marketplace. It also proves our capability to serve customers at any location in the world and deliver the same level of commitment. This doesn’t

mean we are in the process of centralising everything. On the contrary, Omron is focused on being more specialised locally because we recognise the different cultural and communications needs of our customers, and share their challenges in conducting business at a local level.

My message for ECB in Europe, the Middle East, Africa and

Russia is to positively embrace the changes taking place in the market and pay attention to delivering real customer satisfaction through best practice.

To facilitate this objective we are undertaking a serious evaluation of ECB to see what value added services we need to be offering in the area of customer service and support, and in the area of technology and product development. In the latter area, we are expanding our Electromechanical (EM) offerings, with new relay and switch developments expected soon. We are also continuing investment in our Microelectronics (ME) product range, especially our photonics product line in light of exciting advances in the telecom and datacom markets. We are a supplier to some of the major mobile brands in the world and have already had

great success in LED backlights, so you can expect to see some new technologies for the handheld market in the near future. New investment in our connector portfolio makes this another area to keep an eye on. Our new Connector Specialist for Europe (Pg 15) is now on board and new technology is in development that will greatly enhance our connector offerings.

As we move into the final quarter of 2007, our strategy is to accelerate Omron’s sales profile and prepare the organisation for future changes. We are in the process of finalising the third stage of Grand Design (GD) 2010 which involves a focus on certain key technologies and products, investing in specialists in specific market areas and generally striving to make the process of dealing with Omron a ‘pleasant experience’.

We are integrating web based tools, Electronic Data Interchange (EDI) and value added extras into customer service activities. We are also working closely with distributors to involve them in the early stages of customer liaison. Distribution currently represents 30% of Omron’s business and this will continue to grow as we learn new ways to complement each other’s business resources.

*This is an exciting time to join Omron ECB and I look forward to working with you all in a market that is so inspiring and dynamic.*

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